



A-9183  
PATENT APPLICATION

11/19/02  
#6

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of:

Tarak A. RAILKAR et al.

Appln. No.: 10/069,768

Group Art Unit: 2881

Filed: July 8, 2002

For: PASSIVATION OF MATERIAL USING ULTRA-FAST PULSED  
LASER

RECEIVED  
NOV 12 2002  
TECHNOLOGY CENTER 2800

INFORMATION DISCLOSURE STATEMENT

Commissioner for Patents  
Washington, D.C. 20231

Sir:

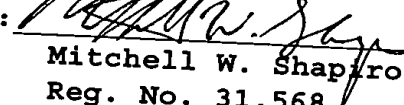
Pursuant to 37 C.F.R. § 1.56, and without any  
assertion as to materiality or prior art effect, the  
documents listed on the attached Form PTO-1449 are hereby  
cited.

The listed documents were cited in the International  
Search Report.

Respectfully submitted,

MWS:sjk

Miles & Stockbridge P.C.  
1751 Pinnacle Drive  
Suite 500  
McLean, Virginia 22102-3833  
(703) 903-9000

By:   
Mitchell W. Shapiro  
Reg. No. 31,568

November 12, 2002

## LIST OF DOCUMENTS CITED BY APPLICANT

Atty. Docket No.

Appln. No.

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10/069,768



Applicant

Tarak A. RAILKAR et al.

Filing Date

Group

July 1, 2002

2881

## U.S. PATENT DOCUMENTS

Examiner Initial	Document Number	Date	Name	Class	Sub-class	Filing Date
AA	6,008,525	12/28/99	Barron et al.	257	629	
AB	5,352,330	10/04/94	Wallace	156	643	
AC	5,665,637	09/09/97	Chand	372	46	
AD	4,406,053	09/27/83	Takasaki et al.	29	588	
AE	5,139,606	08/18/92	Maki	156	643	
AF	5,736,709	04/07/98	Neiheisel	219	121.61	
AG						
AH						
AI						
AJ						

## FOREIGN PATENT DOCUMENTS

Examiner Initial	Document Number	Date	Country	Class	Sub-class	Translation
AK	63-102918	05/07/88	Japan			Abstract
AL						
AM						

OTHER (including author, title, date, pertinent pages, etc.)

AN	N.C. Tien et al., "Surface adhesion reduction in silicon microstructures using femtosecond laser pulses", <u>Appl. Phys. Lett.</u> , 68 (2), 8 January 1996, pp. 197-199.
AO	
AP	

Examiner

Date Considered

EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; draw line through citation if not in conformance and not considered. Include copy of this form with next communication to Applicant.